



RF360
Europe GmbH

Data sheet

BAW filter
5.25 GHz Wi-Fi 6 UNII1-2a

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Ordering code:	B39522B8377L210
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1 Application

- Low-loss BAW RF coexistence filter for 5.25 GHz Wi-Fi 6 UNII1-2a
- 5.25 GHz Wi-Fi 6 UNII1-2a: pass band 5170 – 5330 MHz
- Usable pass band : 160 MHz

2 Features

- Package size $1.4_{\pm 0.05}$ mm $\times$ $1.1_{\pm 0.05}$ mm
- Package height 0.63 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

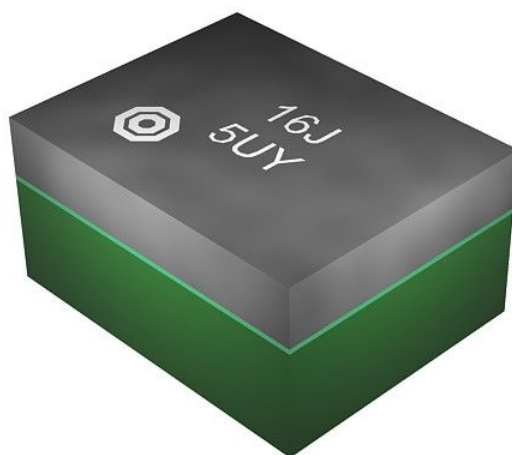
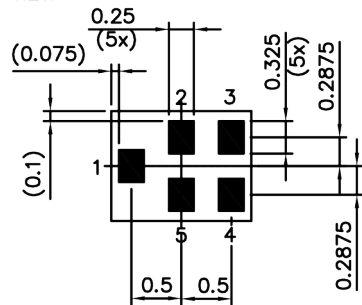


Figure 1: Picture of component with example of product marking.

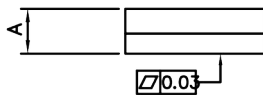
3 Package

BOTTOM VIEW

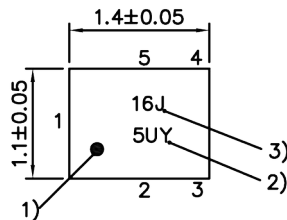


Pad and pitch tolerance ± 0.05

SIDE VIEW

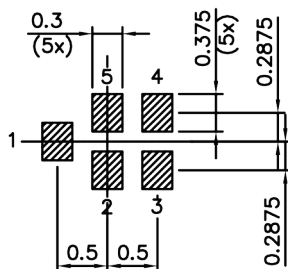


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height $A = 0.63$ mm (max.). See Sec. Package information (p. 17).

4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

5 Matching circuit

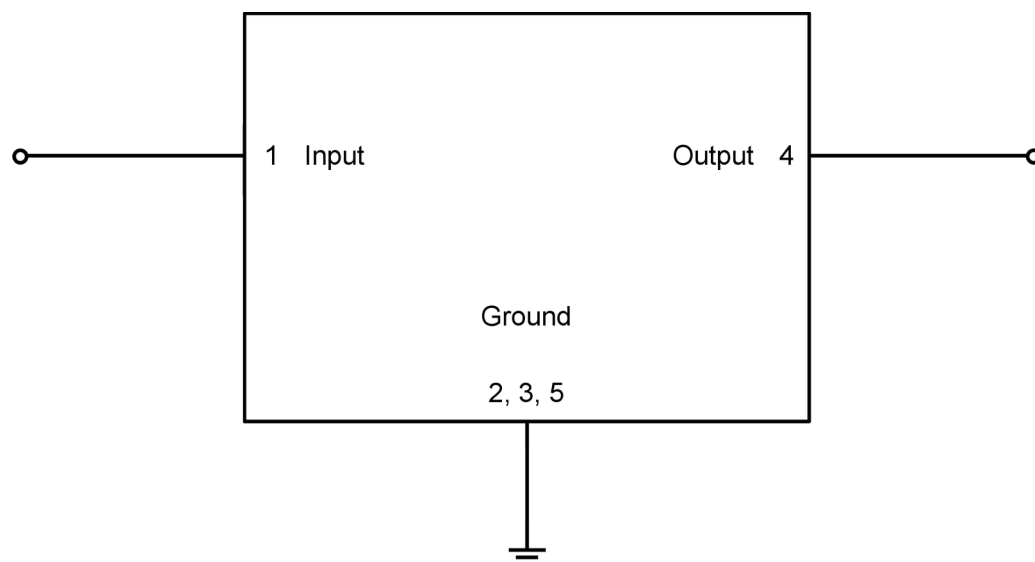


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification

$$T_{\text{SPEC}} = -30\text{ °C} \dots +85\text{ °C}$$

Input terminating impedance

$$Z_{\text{IN}} = 50\ \Omega$$

Output terminating impedance

$$Z_{\text{OUT}} = 50\ \Omega$$

Characteristics			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Maximum insertion attenuation						
	5170... 5330	MHz	—	1.5	2.0	dB
Insertion attenuation – WLAN						
	5170... 5330	MHz	—	1.0	1.9	dB
Amplitude ripple (p-p)						
	5170... 5330	MHz	—	0.6	1.3	dB
Maximum VSWR						
@ input port	5170... 5330	MHz	—	1.4	2.0	
@ output port	5170... 5330	MHz	—	1.4	2.0	
Minimum attenuation						
	30... 2250	MHz	37	40	—	dB
	2250... 2400	MHz	25	30	—	dB
	2400... 2500	MHz	25	30	—	dB
	2500... 3000	MHz	35	39	—	dB
	3400... 3800	MHz	35	41	—	dB
	3800... 4900	MHz	35	37	—	dB
	5490... 5895	MHz	49	54	—	dB
	5945... 6425	MHz	47	53	—	dB
	6425... 7125	MHz	37	45	—	dB
	7203... 7500	MHz	35	42	—	dB
	10340... 10660	MHz	—	33	—	dB

¹⁾ Average over each WLAN channel with band width of 160 MHz.

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +95\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +95\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
ESD voltage		
	$V_{ESD}^{3)} = 500\text{ V (max.)}$	Human body model.
	$V_{ESD}^{4)} = 300\text{ V (max.)}$	Machine model.
Input power	P_{IN}	
@ input port: 5170 ... 5330 MHz	28 dBm	ON-state power of 160 MHz Wi-Fi downlink signal with 70% duty cycle for 27000 h @ 55 °C. Source and load impedance 50 Ω. ⁵⁾
@ input port: other frequency ranges	10 dBm	Continuous wave for 5000 h @ 55 °C. Source and load impedance 50 Ω.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁴⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁵⁾ Expected lifetime according to accelerated power durability tests and wear out models.

8 Transmission coefficient

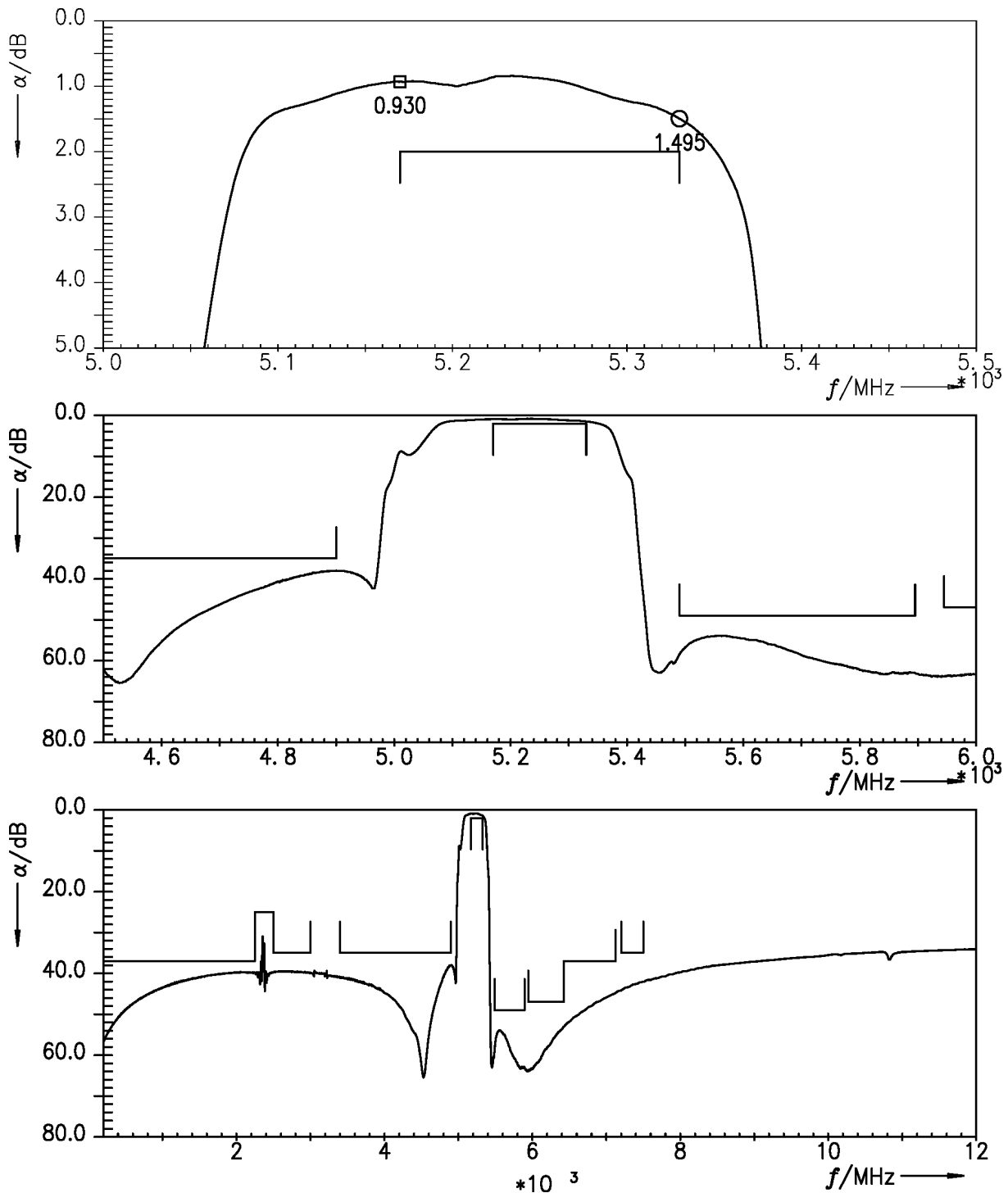


Figure 4: Attenuation.

9 Reflection coefficients

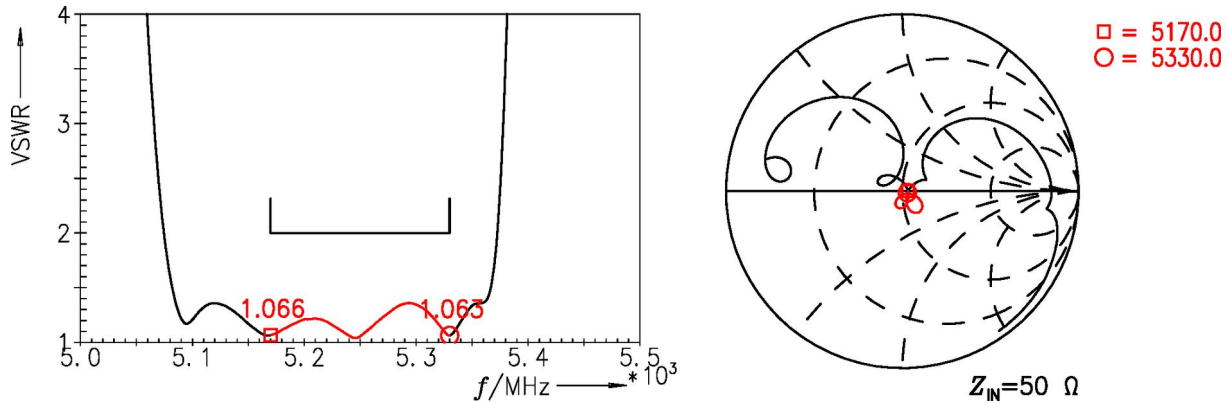


Figure 5: Reflection coefficient at input port.

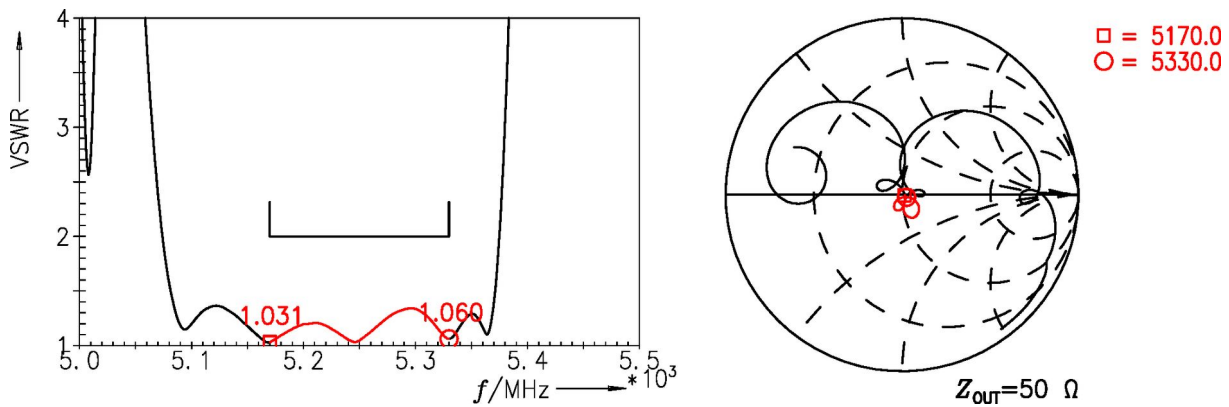


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

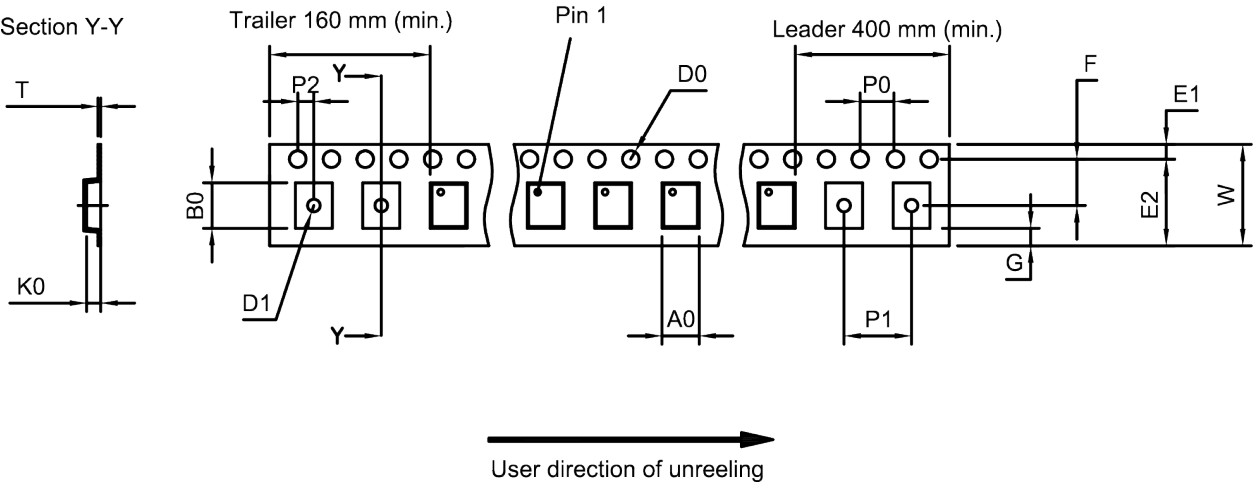


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.25±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	1.55±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	0.5±0.05 mm	K ₀	0.71±0.04 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

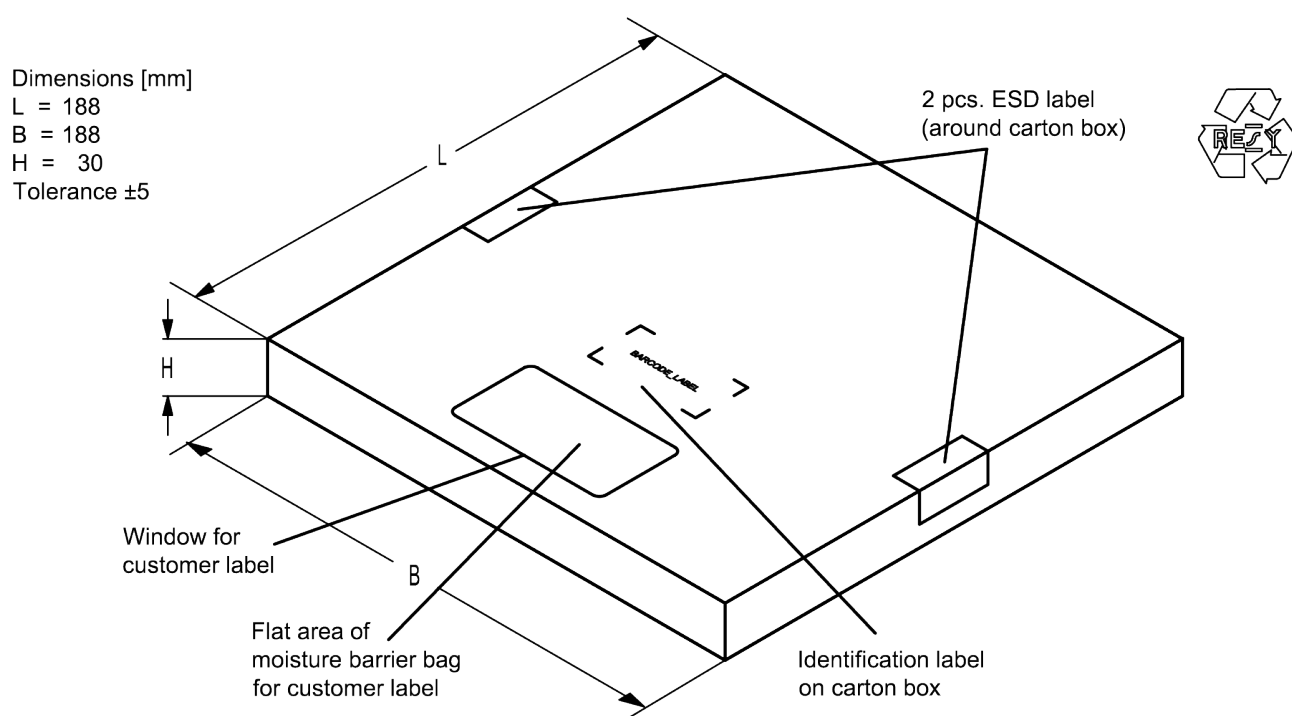


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.
16J $\Rightarrow$ **1234**
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$ **1234**

The BASE32 code for product type B8377 is 85S.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.
5UY $\Rightarrow$ **12345**
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	$\leq 3 \text{ K/s}$
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220 \text{ °C}$	30 s to 70 s
$T > 230 \text{ °C}$	min. 10 s
$T > 245 \text{ °C}$	max. 20 s
$T \geq 255 \text{ °C}$	–
peak temperature T_{peak}	250 °C $\pm 0/-5 \text{ °C}$
wetting temperature T_{min}	230 °C $\pm 5/-0 \text{ °C}$ for $10 \text{ s} \pm 1 \text{ s}$
cooling rate	$\leq 3 \text{ K/s}$
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

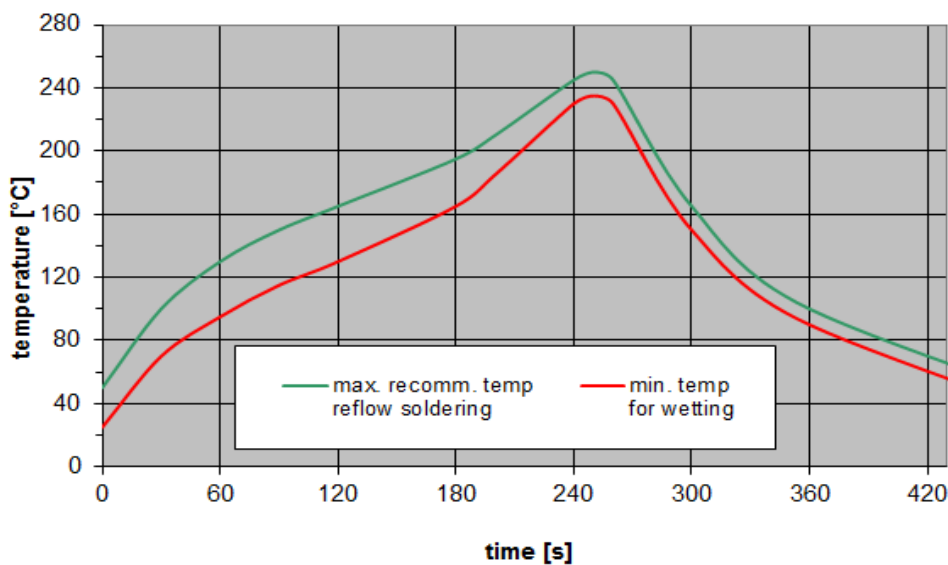


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes, product IDs, labels, and packing units

Ordering code	Product ID	RF360 label	Packing unit
B39522B8377L210	B39522-B8377-L210-W05	B39522B8377L210W 5	5000 pcs

Table 4: Ordering codes / product IDs and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 ESD protection of acoustic devices

Acoustic devices are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies must be applied.

In general, “ESD matching” must be ensured at that electrical port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the acoustic device must be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band acoustic devices the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and input port. The required component values must be determined from case to case.

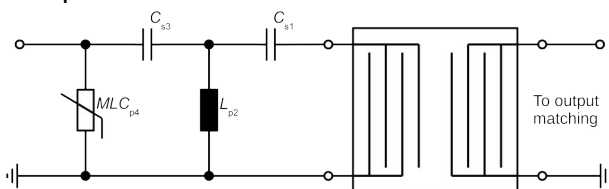


Figure 12: MLC varistor plus ESD matching.

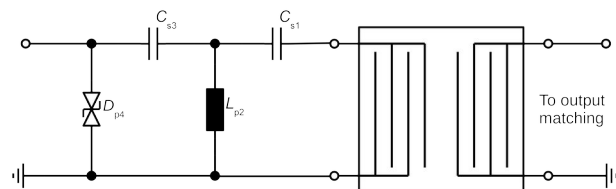


Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

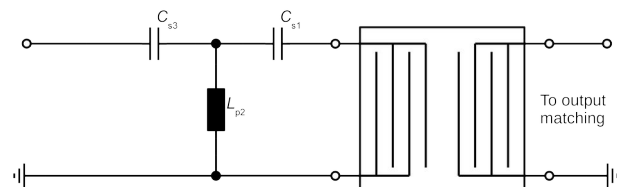


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: “**ESD protection for SAW filters**”. This report can be found under <https://rffe.qualcomm.com>.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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